

IN THE ABSTRACT:

Please DELETE the Abstract in its entirety and substitute the attached new Abstract.

A circuit arrangement placed on a substrate has at least one semiconductor component arranged on the substrate and having at least one electrical contact surface and at least one connection line also arranged on the substrate and used to electrically contact the contact surface of the semiconductor component. The connection line forms part of a discrete, passive electrical component arranged on the substrate. The electrical contacting of the contact surface of the semiconductor component is carried out during a step of the process and the part of the discrete, passive electrical component is produced. To this end, especially a film consisting of an electrically insulating material is applied to the power semiconductor and to the substrate under a vacuum, and the contact surface of the power semiconductor is then bared. Furthermore, the connection component is carried out and the part of the discrete, passive electrical component is produced.